



# P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ ) Max.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 20	0.078 at V <sub>GS</sub> = - 4.5 V	- 1.4			
	0.098 at V <sub>GS</sub> = - 2.5 V	- 1	12.1 nC		
	0.130 at V <sub>GS</sub> = - 1.8 V	- 1	12.1110		
	0.188 at V <sub>GS</sub> = - 1.5 V	- 0.3			

### **FEATURES**

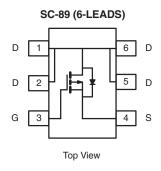
- TrenchFET® Power MOSFET
- Typical ESD Performance 2500 V
- 100 % R<sub>g</sub> Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

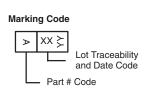


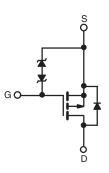
HALOGEN FREE

### **APPLICATIONS**

- Load Switch for Portable Devices
- Power Management







Ordering Information: Si1077X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 20	V			
Gate-Source Voltage		V <sub>GS</sub>	± 8	v		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>A</sub> = 25 °C	1-	- 1.75 <sup>b, c</sup>			
Continuous Diam Current (1) = 130 C)	T <sub>A</sub> = 70 °C	l <sub>D</sub>	- 1.4 <sup>b, c</sup>	^		
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	- 8	A		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.28 <sup>b, c</sup>			
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.33 <sup>b, c</sup>	W		
Maximum Fower Dissipation	T <sub>A</sub> = 70 °C	' D	0.21 <sup>b, c</sup>			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian de Ambiento	t ≤ 5 s	R <sub>thJA</sub>	300	375	°C/W	
Maximum Junction-to-Ambient <sup>a, b</sup>	Steady State		360	450	C/VV	

- a. Maximum under steady state conditions is 450  $^{\circ}\text{C/W}.$
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.

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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 11		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μΑ		2.4			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.4		- 1	V	
Cata Sauraa Laakaga	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 10		
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1		
Zava Cata Valtaga Dvain Curvant	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.8 A		0.065	0.078	Ω	
Due to Course On Otata Bastata and	<b>D</b>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1 A		0.081	0.098		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.100	0.130		
		V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.3 A		0.125	0.188		
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 1.8 A		10		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			965		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		110			
Reverse Transfer Capacitance	C <sub>rss</sub>			101			
Total Cata Charge	Qg	$V_{DS} = -10 \text{ V}, V_{GS} = -8 \text{ V}, I_{D} = -1.75 \text{ A}$		20.7	31.1		
Total Gate Charge				12.1	18.2	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.75 \text{ A}$		1.85			
Gate-Drain Charge	Q <sub>gd</sub>			2.21			
Gate Resistance	$R_g$	f = 1 MHz	3.6	18	36	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			24	36	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_{L} = 7.1 \Omega$		17	26		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -1.4 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		95	145		
Fall Time	t <sub>f</sub>			28	42		
Turn-On Delay Time	t <sub>d(on)</sub>			5	10		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_{L} = 7.1 \Omega$		8	16	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -1.4 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		115	173		
Fall Time	t <sub>f</sub>			26	39		
Drain-Source Body Diode Characteris	stics						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 8	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 1.4 A		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			16	24	ns	
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		I <sub>F</sub> = - 1.4 A, dI/dt = 100 A/μs		7	14	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	1 = - 1.4 Λ, α//αι = 100 Α/μδ		9			
Reverse Recovery Rise Time	t <sub>b</sub>			7		ns	

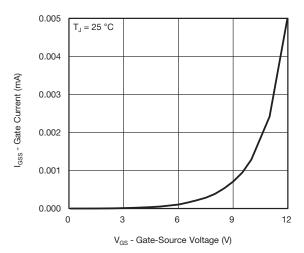
### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

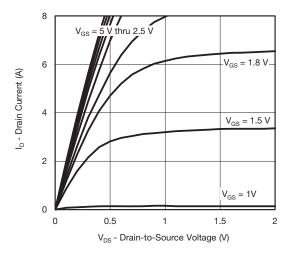
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



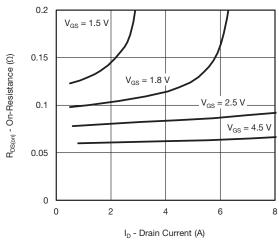
# **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



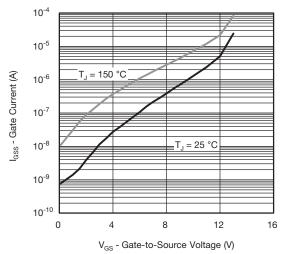
### Gate Current vs. Gate-Source Voltage



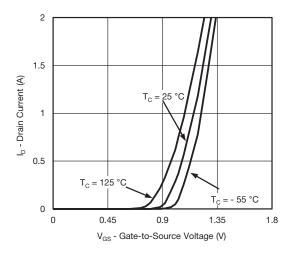
### **Output Characteristics**



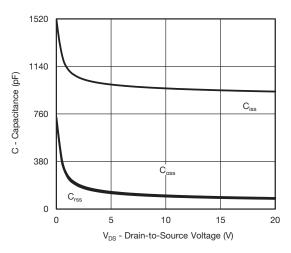
On-Resistance vs. Drain Current



Gate Current vs. Gate-to-Source Voltage



Transfer Characteristics Curves vs. Temperature

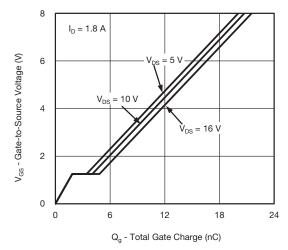


Capacitance

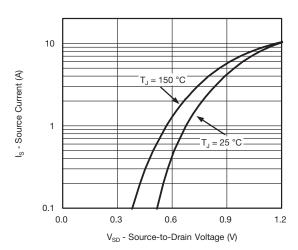
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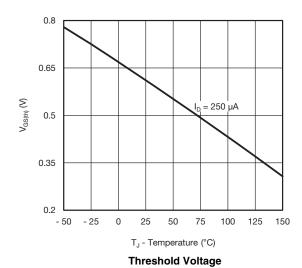
# **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

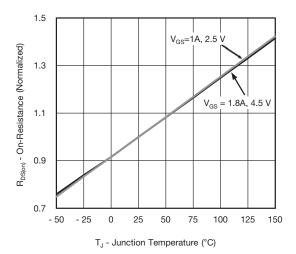


### **Gate Charge**

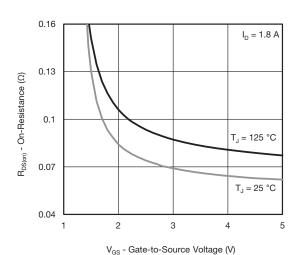


### Source-Drain Diode Forward Voltage

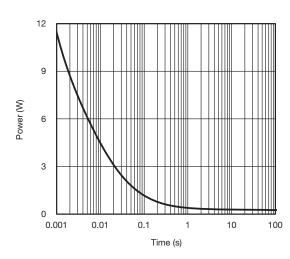




On-Resistance vs. Junction Temperature



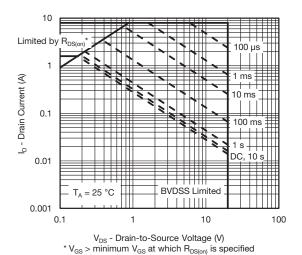
On-Resistance vs. Gate-to-Source Voltage

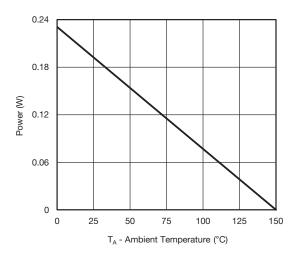


Single Pulse Power, Junction-to-Ambient



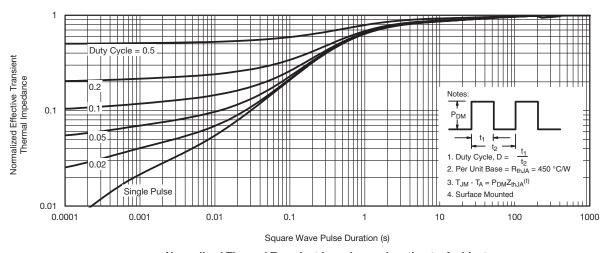
# **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

**Power Junction-to-Ambient** 

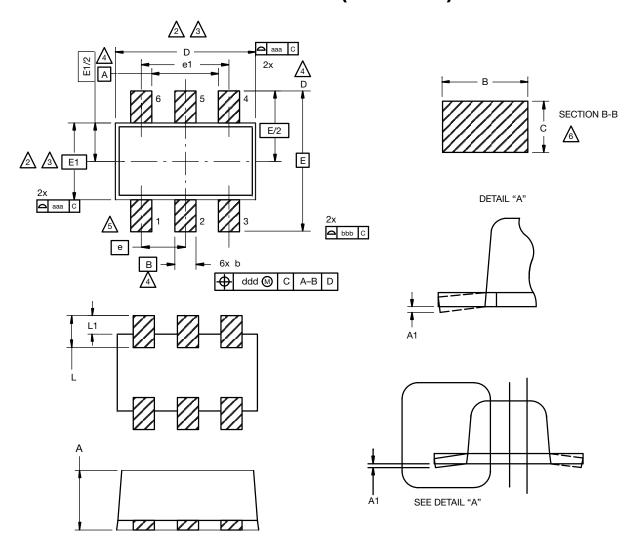


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63254.



# **SC-89 6-Leads (SOT-563F)**



### Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

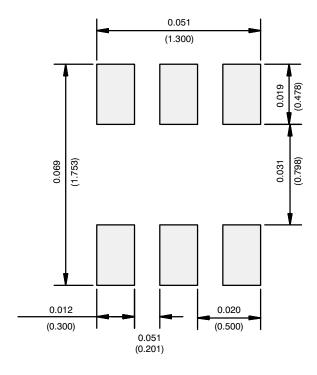
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
DIW.	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			
C14-0439-Rev. C, 11-Aug-14 DWG: 5880						



### **RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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